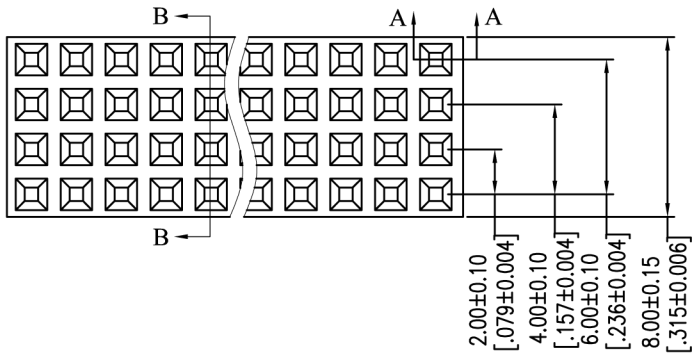
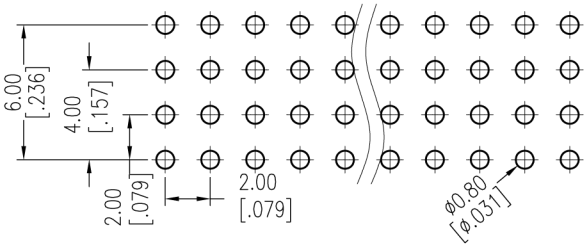
HSF

NOTES:
Current Rating: 2.0AMP
Contact Resistance: 20mΩ Max
Withstand Voltage: 500V AC/DC
Insulation Resistance: 1000MΩ Min
Operation Temperature: −40℃ to +105℃

Contact Material:Phosphor Bronze
Contact plating:Au Or Sn over Ni
Insulator Material:LCP+30%G.F UL94V−0



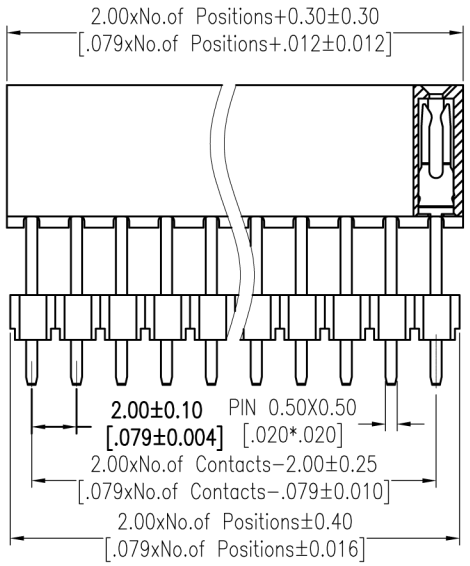
Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE±0.05)



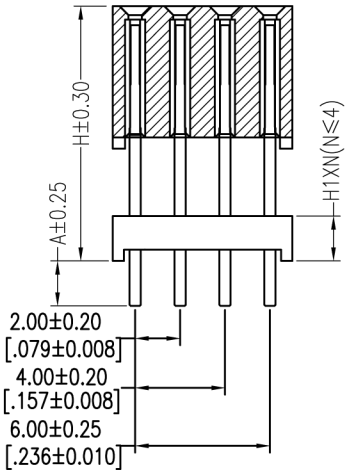
Ordering Information

2263D - 4 XX S XX D Y N X X

- No.of Pins per ROW:02~40PIN
- Contact Plating:
  G0=Gold Flash
  G3=10μ"Gold
  G4=15μ"Gold
  G5=30μ"Gold
  S0=Gold Flash/Tin
  S3=10μ"Gold/Tin
  S4=15μ"Gold/Tin
  S5=30μ"Gold/Tin
  SN=Tin
  SM=Matte Tin
- Insulator: D=LCP
- Packing: T=Tube A=Tray



SECTION A−A



SECTION B−B

Item	Pitch	Mating
Standard	2.00	1215/1220
Alternate		

DIMENSION ANTITHESES LIST			
H1XN(N≤4)	A	H	H1
STANDARD	2.28	9.35	1.50
ALTERNATE			

REV	DATE	MODIFICATION DESCRIPTION	CHANGE
A1	2013/04/26	Modify drawing	------
A0	2012/12/07	NEW	------

OPERATION	
X.X	±0.40
X.XX	±0.25
X.XXX	±0.15
Angle	± 3°
DIM	TOL

DRAW	Wang	DATE	2013/04/26
CHECK		DATE	
APPROVE		DATE	

SCALE	FIT
UNIT	mm
SIZE	A4
SHEET	1/1
PROJ.	

PART NO. 2263D-4XXSXXDYNXX

TITLE: FH2.00mm FOUR ROW 180° DIP H=6.35+HOUSING

Customer NO.

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